Driving decarbonization and digitalization. Together.

Principal Engineer for Pinout Architecture, Packaging, and Product Variant Management - Microcontroller (f/m/div)

Job description

Infineon has ambitious plans to develop our next automotive microcontroller (MCU) product generation. Do you want to shape the future of smarter, safer and connected cars by solving complex technical challenges? Do you want to shape the future of smarter, safer and cleaner connected cars by solving complex technical challenges? Then we have a great opportunity for you! As Principal Engineer for Pinout, package and product variant management, you will act as a key driver in our Platform Architecture team to define scalable architecture solutions of our novel automotive platforms. With this position you will join our Technical Ladder: a special career path for those who share innovative ideas, demonstrate comprehensive technical knowledge, show thought leadership, possess problem solving abilities and are able to create business value.

In your new role you will:

- **Define** a competitive and scalable **package and pinout architecture** for our next generation product portfolio, ranging from high-performance MCUs with GHz Class CPUs down to power/cost optimized general purpose automotive MCUs
- **Develop a platform solution for functional pinout assignment**, which fits to all platform related packages, covers all product configurations and serves compatibility requirements to previous platforms and within a product family
- **Drive feasibilities to ensure routability** of the defined packages using common and cost-effective automotive PCB technologies considering customer needs and marketing inputs for our wide set of applications
- **Provide requirements to the package technology development** (e.g. functional /fanout and thermal) and package development (e.g. package substrate routing)
- **Document the overall configuration space and drive appropriate methodologies** to master the complexity given by application-specific silicon dies and their dedicated functions, different package variants and pin configurations
- **Collaborate with and guide development teams** during SoC floorplan, pad-frame feasibility studies and package routing
- **Drive System-in-a-package** as new integration paradigm together with a **cross-functional team** of experts with respect to pads/pinning/package opportunities.
- **Cooperate closely with expert teams** such as platform lead architects, subsystem architects, package-technology experts, SW development, design teams, and other business lines within Infineon

At a glance

Location:	**Munich (Germany), Langen (Frankfurt am Main) (Germany)**
Job ID:	**HRC0540148**
Start date:	**as soon as possible**
Entry level:	**5+ years**
Type:	**Full time**
Contract:	**Permanent**

Apply to this position online by following the URL and entering the Job ID in our job search. Alternatively, you can also scan the QR code with your smartphone:

Job ID: **HRC0540148**
www.infineon.com/jobs

Contact

Florian Nops
Recruiter

Profile

You have a clear notion of how innovation contributes to the commercial success of the company, you constantly gain new insights by questioning existing assumptions and you inspire others for your ideas explaining even complex issues in a clear and convincing manner. Furthermore, you accept responsibility and accountability for decisions, and you are open to new challenges without knowing the right path to a solution in advance. If you remain aware of the big picture even in complex situations and take decisions despite uncertain circumstances, then you should join our team!

You are best equipped for this task if you have:

- A **Degree in Electrical Engineering**, **Computer Engineering**, **Physics** or a related field
- At least **6 years of experience** as **platform/SoC architect**, **concept**, or **system engineer** in the area of **MCU/SoC development** or **automotive ECU development**
- Profound understanding of **MCUs for automotive applications**, their interfaces and product family aspects
- Very good understanding of **state-of-the art ECU HW-development challenges and solutions** incl. bill-of-material aspects
- Experience in **PCB technologies**, **PCB design** and **layout**
- Experience in **signal and power integrity** and their effects on ball-out, pin-out and PCB routing (e.g. for high speed communication)
- Good understanding in **mixed-signal functions** and **powers supplies**, state-of the art **highspeed communication** and **memory interfaces**
- Hands-on experience in **product architecture documentation** and **requirements management**
- **Functional Safety and Security** experience is a plus (e.g. experience with development according to ISO26262 or IEC61508 and ISO21434)
- Ability to **understand platform development trade-offs** and **negotiate with different stakeholders**
- Excellent **technical leadership capabilities** combined with **good communication skills**
- The ability to work in **cross-functional teams** and a **multi-cultural environment**
- Fluent **English** communication is a must; **German** is appreciated

Benefits

- **Munich:** Coaching, mentoring networking possibilities; Wide range of training offers & planning of career development; International assignments; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Flexible working conditions; Home office options; Part-time work possible (also during parental leave); Sabbatical; On-site creche and kindergarden with 220 spots, open until 5:30pm; Holiday child care; On-site social counselling and works doctor; Health promotion programs; On-site gym, jogging paths, beachvolleyball, tennis & soccer court; On-site canteen; Private insurance offers; Wage payment in case of sick leave; Corporate pension benefits; Flexible transition into retirement ; Performance bonus; Reduced price for public transport and very own S-Bahn station; Access for wheelchairs; Possibility to work remotely from abroad (EU)

Why Us

Driving decarbonization and digitalization. Together.

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard

components to special components for digital, analog, and mixed-signal applications to customer-specific solutions together with the appropriate software.

– Automotive (ATV) shapes the future of mobility with microelectronics enabling clean, safe, and smart cars –

The ATV division is shaping the future of mobility by enabling clean, safe, and smart cars. Its product and solution offering is powering the decarbonization and digitalization of vehicles. By driving the transition to hybrid and purely electric vehicles, ATV is making a valuable contribution to cleaner roads. ATV is also increasingly digitalizing cockpit, infotainment, comfort, and lighting applications as it takes automated driving to the next stage with higher levels of connectivity, security, and safety.

The ATV portfolio integrates sensors, microcontrollers, high-performance memories for specific applications, power semiconductors based on silicon and silicon carbide, as well as components for human-machine interaction and vehicle connectivity. Infineon is the world leader in automotive semiconductors.

Click here for more information about working at ATV with interesting employee and management insights and an overview with more #ATVDreamJobs.

Automotive Microcontroller: We make green mobility smart

As a leading automotive microcontroller vendor, the Infineon business line Automotive Microcontroller (ATV MC) offers the industry's most comprehensive microcontroller and software portfolio. The three major product families, AURIX, TRAVEO and PSoC, provide the newest innovation in performance, connectivity, power consumption, safety and security.

We enable the latest advancements in the dynamic automotive market, such as vehicle electrification, automated driving and driver information & interaction. Being at the core of transformation, we pave the way for new technologies, such as artificial intelligence and dependable computing, as well as higher levels of connectivity, security and user experience. So, join us to create a better future together.
#AutomotiveMicrocontroller

We are on a journey to create the best Infineon for everyone.

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness, respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant´s experience and skills.

We look forward to receiving your resume, even if you do not entirely meet all the requirements of the job posting.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

Click here for more information about Diversity & Inclusion at Infineon.